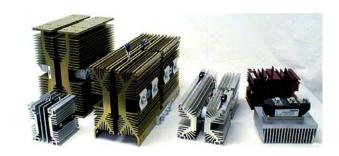
Integrated Power Structures

Powerex, a world leader in power semiconductor manufacturing, offers a complete array of Standard and Application Specific Integrated Power Structures.

Standard Rectifier / Thyristor Assemblies

Powerex has developed a wide lineup of standard air or liquid cooled rectifier / thyristor assemblies in all common circuit configurations utilizing either discrete disk or isolated baseplate power semiconductors. A range of standard extrusions or copper chill blocks and clamps are used to produce a comprehensive range of assemblies rated from 100 to 6000A DC output in air cooled and 400 to 15,000A DC output when liquid cooled.



Engineered Solutions

When standard assemblies are not sufficient, the Powerex engineering team is prepared to design and manufacture power semiconductor assemblies to specific application requirements. These engineered solutions provide the optimum solution to electrical, thermal, or mechanical challenges. Beyond a heatsink engineered for the thermal requirements of the application; fuses, thermal sensors, terminal blocks, insulators, bus bars, snubbers, fans, and gate drive circuits can also be integrated into definite purpose assembly designs.



IGBT Assemblies

Powerex also produces assemblies integrating IGBT or IPM modules including the POW-R-PAK family of configurable power assemblies. The POW-R-PAK features a high performance IGBT inverter bridge with gate drive, fault detection, low inductance bus, DC link capacitor bank, and output current measurement, with an integral air or liquid cooled heatsink. The POW-R-PAK may be used as a converter, chopper, half or full bridge in a variety of power conversion applications from 25 to 1500 kW.





173 Pavilion Lane Youngwood, PA 15697-1800 Phone: 724-925-7272 Fax: 724-925-4393 Internet: www.pwrx.com



<u>Powerex Assembly Design Guide</u>
Please fill out form and fax it back to the attention of Kelly Bandieramonte (724)925-4393

Compa	any Name:					
Contac	ct:					
Addres	ss:					
City: _				State:	Zip:	
Fax:						
Fnone	<u> </u>					
E-maii	:					
Applica	ntion:					
Voltage						
	Max Voltage:		Vrms			
	Max Transient:		V			
	Safety Factor		%			
Current						
	Nominal Output C					
	Dester Occale		.,			
	Duty Cycle: Overload Current		%			
	Pulse Width					
	Duration					
Cooling ☐Air	Method:	deg	rees C			
	Airflow	_ CFM				
☐ Liqu	iid					
	Max Liquid Temp. Flow Rate C	degree PM	es C			
Mechar	nical:					
	Max Length					
	Width Height					
	Mounting Method	:				
	☐ Insulated					
	Non-Insulated					
	non modiated					
Wavefo	orm:					
						_ ,
Other C	Comments:					